

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently Amended) A socket for a semiconductor device comprising:  
a contact sheet having a plurality of bumps to be electrically connected to a terminal group of a semiconductor device, for inputting/outputting signals relative to the semiconductor device;

a pressing member for pressing terminals of the semiconductor device onto the bumps of the contact sheet;

an accommodation portion for accommodating the semiconductor device disposed on said contact sheet; and

a movement-amount controlling member, provided as part of said contact sheet and not electrically connectable to the terminal group, for controlling a movement amount of said semiconductor device along the direction of a projected height of said bump when said pressing member disposed in said accommodation portion is in a pressed state[[:]].

wherein said movement-amount controlling member is disposed on top of said contact sheet.

2. (Currently Amended) A socket for a semiconductor device comprising:  
a contact sheet having a bump group to be electrically connected to a terminal group of [[a]] said semiconductor device, for inputting/outputting signals relative to said semiconductor device;

a pressing member for pressing terminals of said semiconductor device onto a bump group of said contact sheet; and

a contact sheet pressing member for pressing said contact sheet in ~~[[the]]~~ a direction ~~in which the~~ of a sinking of said contact sheet in the vicinity of said bump group is restricted when the terminals of said semiconductor device are pressed onto said bump group by said pressing member~~[[;]]~~.

wherein said contact sheet pressing member engages the top of the contact sheet.

3. (Previously Presented) A socket for a semiconductor device as claimed in claim 2, wherein said contact sheet pressing member is disposed in an accommodation portion for accommodating said semiconductor device and is formed integral with said pressing member.

4. (Original) A socket for a semiconductor device as claimed in claim 2, wherein an elastic sheet having the elasticity is disposed directly beneath said contact sheet.

5. (Currently Amended) A socket for a semiconductor device comprising:  
a contact sheet having a bump group to be electrically connected to a terminal group of ~~[[a]]~~ said semiconductor device, for inputting/outputting signals relative to said semiconductor device~~[[,]]~~;

a pressing member for pressing ~~terminals~~ said terminal group of said semiconductor device onto a bump group of said contact sheet~~[[,]]~~; and

a sinking-amount adjustment section formed opposite to said bump group of said contact sheet, for compensating an amount of sinking of said bump group by applying a force in a direction opposite to the sinking when said ~~terminals~~ terminal group of said semiconductor device is pressed by said pressing member.

6. (Original) A socket for a semiconductor device as claimed in claim 5, wherein an elastic sheet having the elasticity is disposed directly beneath said contact sheet.

7. (Previously Presented) A socket for a semiconductor device as claimed in claim 5, wherein the sinking-amount adjustment section includes at least one convex seat portion formed on a surface layer of said contact sheet opposite to said bump group.

8. (Previously Presented) A socket for a semiconductor device as claimed in claim 5, wherein the sinking-amount adjustment section includes at least one convex seat portion formed on a bottom of an accommodation portion for accommodating said semiconductor device via said contact sheet.

9. (Currently Amended) A socket for a semiconductor device comprising:  
a contact sheet having a plurality of bumps to be electrically connected to a terminal group of a semiconductor device, for inputting/outputting signals relative to said semiconductor device[[],],

a pressing member for pressing terminals of said semiconductor device onto said bumps of said contact sheet[[],];

an accommodation portion for accommodating said semiconductor device disposed on said contact sheet[[,]]; and

a movement-amount restricting member, provided as part of said contact sheet and electrically isolated from the terminal group, for restricting a movement amount of said semiconductor device along the direction of a projected height of said bump when said pressing member disposed in said accommodation portion is in a pressed state[[:]],

wherein said movement-amount restricting member is disposed on top of said contact sheet.

10. (Original) A socket for a semiconductor device as claimed in claim 9, wherein said movement-amount restricting member is provided in a region of said contact sheet in the vicinity of said bumps and opposite to said semiconductor device.

11. (Original) A socket for a semiconductor device as claimed in claim 10, wherein said movement-amount restricting member is made of material having high rigidity compared with that of said bump.

12. (Original) A socket for a semiconductor device as claimed in claim 10, wherein said movement-amount restricting member is made of elastic material.

13. (Currently Amended) A socket for a semiconductor device comprising:  
a contact sheet having a bump group to be electrically connected to a terminal group of [[a]] said semiconductor device, for inputting/outputting signals relative to said semiconductor device;

a pressing member for pressing ~~terminals~~ said terminal group of said semiconductor device onto a bump group of said contact sheet; and

a sinking-amount adjustment section formed opposite to said bump group of said contact sheet, for adjusting an amount of sinking of said bump group when said ~~terminals~~ terminal group of said semiconductor device is pressed by said pressing member[[:]],

wherein the sinking-amount adjustment section includes at least one convex seat portion formed on a surface layer of said contact sheet opposite to said bump group.

14. (Currently Amended) A socket for a semiconductor device comprising:  
a contact sheet having a bump group to be electrically connected to a terminal group of [[a]] said semiconductor device, for inputting/outputting signals relative to said semiconductor device[[:]];

a pressing member for pressing ~~terminals~~ said terminal group of said semiconductor device onto a bump group of said contact sheet[[:]]; and

a sinking-amount adjustment section formed opposite to said bump group of said contact sheet, for adjusting an amount of sinking of said bump group when said ~~terminals~~ terminal group of said semiconductor device is pressed by said pressing member[[:]].

wherein the sinking-amount adjustment section includes at least one convex seat portion formed on a bottom of an accommodation portion for accommodating said semiconductor device via said contact sheet.

15. (Previously Presented) A socket for a semiconductor device as claimed in claim 1, wherein said movement-amount controlling member is formed to be integral with a surface layer of said contact sheet opposite to said bump group.

16. (Previously Presented) A socket for a semiconductor device as claimed in claim 1, said movement-amount controlling member is formed to be integral with part of said accommodation portion under said contact sheet.

17. (New) A socket for a semiconductor device comprising:  
a contact sheet having a bump group to be electrically connected to a terminal group of said semiconductor device, for inputting/outputting signals relative to said semiconductor device;  
a pressing member for pressing said terminal group of said semiconductor device onto a bump group of said contact sheet; and  
a contact sheet pressing member for pressing said contact sheet in ~~[[the]]~~ a direction ~~in which the~~ of a sinking of said contact sheet in a vicinity of said bump group is restricted when the terminal group of said semiconductor device is pressed onto said bump group by said pressing member,  
wherein said contact sheet pressing member engages the contact sheet, and  
wherein said contact sheet pressing member is disposed in an accommodation portion for accommodating said semiconductor device and is formed integral with said pressing member.

18. (New) A socket for a semiconductor device comprising:

a contact sheet having a bump group to be electrically connected to a terminal group of a semiconductor device, for inputting/outputting signals relative to said semiconductor device;

a pressing member for pressing terminals of said semiconductor device onto ~~[[a]]~~ said bump group of said contact sheet; and

a contact sheet pressing member for pressing said contact sheet together with said pressing member ~~in the a direction in which the~~ of a sinking of said contact sheet in the vicinity of said bump group is restricted and said pressing member presses terminals of said semiconductor when the terminals of said semiconductor device are pressed onto said bump group by said pressing member; ~~and,~~

wherein said contact sheet pressing member engages the top of the contact sheet.

19. (New) A socket for a semiconductor device comprising:

a contact sheet having a plurality of bumps to be electrically connected to a terminal group of said semiconductor device, for inputting/outputting signals relative to said semiconductor device,

a pressing member for pressing terminals of said semiconductor device onto said bumps of said contact sheet;

an accommodation portion for accommodating said semiconductor device disposed on said contact sheet; and

a movement amount restricting member, provided as part of said contact sheet and electrically isolated from the terminal group, for restricting a movement amount of

said semiconductor device along a direction of a projected height of said bump when said pressing member disposed in said accommodation portion is in a pressed state, wherein said movement amount restricting member is disposed on top of said contact sheet and said movement amount restricting member is a dummy bump engaged with said semiconductor device or said pressing member.

20. (New) A socket for a semiconductor device comprising:
- a contact sheet having a plurality of bumps to be electrically connected to a terminal group of a semiconductor device, for inputting/outputting signals relative to said semiconductor device;
  - a pressing member for pressing terminals of said semiconductor device onto said bumps of said contact sheet;
  - an accommodation portion for accommodating said semiconductor device disposed on said contact sheet; and
  - a movement amount restricting member for restricting a movement amount of said semiconductor device along a direction of a projected height of said bump when said pressing member disposed in said accommodation portion is in a pressed state, wherein said movement amount restricting member is disposed on top of said contact sheet and said movement amount restricting member interferes with said semiconductor device or said pressing member.